

Co-designing electronics with microfluidics for more su

Nature

585, 211-216

DOI: [10.1038/s41586-020-2666-1](https://doi.org/10.1038/s41586-020-2666-1)

Citation Report

#	ARTICLE	IF	CITATIONS
1	Effects of constructal theory on thermal management of a power electronic system. Scientific Reports, 2020, 10, 21436.	1.6	7
2	Materials and Interface Challenges in High-Vapor-Quality Two-Phase Flow Boiling Research. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2021, 11, 1583-1591.	1.4	16
3	Modeling and Numerical Investigation of Transient Two-Phase Flow with Liquid Phase Change in Porous Media. Nanomaterials, 2021, 11, 183.	1.9	6
4	Advances in thermal conductivity for energy applications: a review. Progress in Energy, 2021, 3, 012002.	4.6	24
5	Topological effects of phonons in GaN and AlGaN: A potential perspective for tuning phonon transport. Journal of Applied Physics, 2021, 129, .	1.1	17
6	Sustainable electronics product design and manufacturing: State of art review. International Journal of Sustainable Engineering, 2021, 14, 541-551.	1.9	7
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17	Bioinspired perovskite quantum dots microfibers from microfluidics. Science China Materials, 2021, 64, 2858-2867.	3.5	5
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